

MECHANICAL CASE OUTLINE

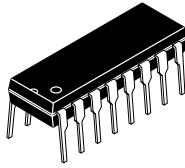
PACKAGE DIMENSIONS

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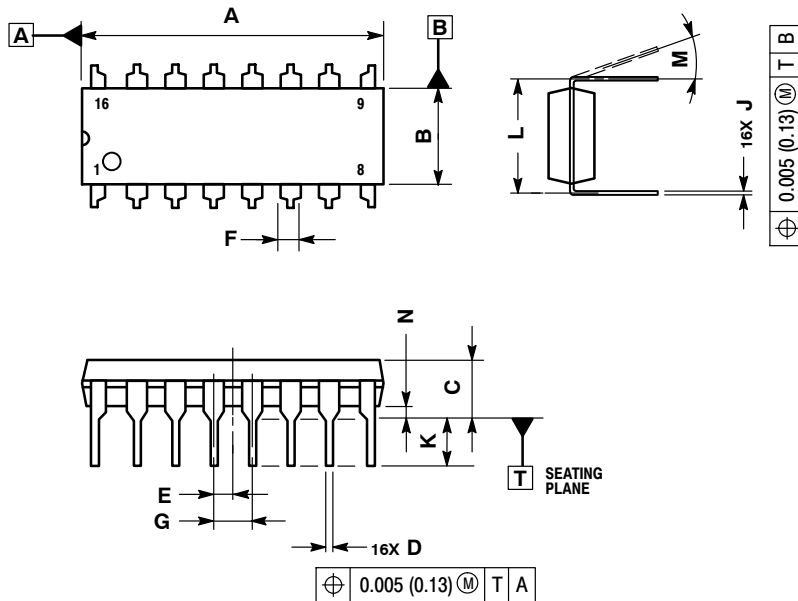


PDIP CASE 648C-04 ISSUE D

DATE 07/28/1998



SCALE 1:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.744	0.783	18.90	19.90
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
E	0.050 BSC		1.27 BSC	
F	0.040	0.70	1.02	1.78
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0°	10°	0°	10°
N	0.015	0.040	0.39	1.01

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